



BSI Standards Publication

Materials for printed boards and other interconnecting structures

Part 2-53: Reinforced base materials clad and unclad — PTFE unfilled laminate sheets of defined flammability (vertical burning test), copper-clad

National foreword

This British Standard is the UK implementation of EN IEC 61249-2-53:2025. It is identical to IEC 61249-2-53:2025.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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Amendments/corrigenda issued since publication

Date	Text affected
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English Version

Materials for printed boards and other interconnecting structures
- Part 2-53: Reinforced base materials clad and unclad - PTFE
unfilled laminate sheets of defined flammability (vertical burning
test), copper-clad
(IEC 61249-2-53:2025)

Matériaux pour circuits imprimés et autres structures
d'interconnexion - Partie 2-53: Matériaux de base renforcés,
métallisés et non métallisés - Feuilles stratifiées non
chargées en PTFE d'inflammabilité définie (essai de
combustion verticale), plaquées cuivre
(IEC 61249-2-53:2025)

Werkstoffe für Leiterplatten und andere
Verbindungsstrukturen - Teil 2-53: Kaschierte und
unkaschierte verstärkte Basismaterialien - ungefüllte PTFE-
Laminattafeln mit definierter Brennbarkeit (Brennprüfung mit
vertikaler Prüflingslage), kupferkaschiert
(IEC 61249-2-53:2025)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

The text of document 91/1978/CDV, future edition 1 of IEC 61249-2-53, prepared by TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61249-2-53:2025.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2026-11-30 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2028-11-30 document have to be withdrawn

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Endorsement notice

The text of the International Standard IEC 61249-2-53:2025 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61189-2	2006	Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2: Test methods for materials for interconnection structures	EN 61189-2	2006
IEC 61189-2-721	2015	Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-721: Test methods for materials for interconnection structures - Measurement of relative permittivity and loss tangent for copper clad laminate at microwave frequency using a split post dielectric resonator	EN 61189-2-721	2015
IEC 61189-2-803	2023	Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-803: Test methods for Z-axis expansion of base materials and printed boards	EN IEC 61189-2-803	2023
IEC 61189-2-807	2021	Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-807: Test methods for materials for interconnection structures - Decomposition temperature (T_d) using TGA	EN IEC 61189-2-807	2021
IEC 61189-2-809	2024	Test methods for electrical materials, circuit boards and other interconnection structures and assemblies - Part 2-809: X/Y coefficient of thermal expansion (CTE) test for thick base materials by TMA	EN IEC 61189-2-809	2025

EN IEC 61249-2-53:2025 (E)

IEC 61249-5-1	-	Materials for interconnection structures - Part 5: Sectional specification set for conductive foils and films with and without coatings - Section 1: Copper foils (for the manufacture of copper-clad base materials)	EN 61249-5-1	-
IEC 61249-6-3	2023	Materials for printed boards and other interconnecting structures - Part 6-3: Sectional specification set for reinforcement materials - Specification for finished fabric woven from "E" glass for printed boards	EN IEC 61249-6-3	2023
ISO 11014	2009	Safety data sheet for chemical products - Content and order of sections	-	-
IPC TM-650 2.5.5.5	TM	- Stripline Test for Permittivity and Loss Tangent (Dielectric Constant and Dissipation Factor) at X-Band	-	-

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